TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK3313

# Chopper Regulator, DC-DC Converter Applications Motor Drive Applications

• Fast reverse recovery time  $t_{rr} = 90 \text{ ns (typ.)}$ 

• Built-in high-speed free-wheeling diode

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & : R_{DS}\ (ON) = 0.5\ \Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & : |Y_{fs}| = 8.5\ S\ (typ.) \\ \bullet & Low\ leakage\ current & : I_{DSS} = 100\ \mu A\ (max)\ (V_{DS} = 500\ V) \\ \bullet & Enhancement-mode & : V_{th} = 2.0 \sim 4.0\ V\ (V_{DS} = 10\ V,\ I_{D} = 1\ mA) \end{array}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteri	stics	Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	500	V
Drain-gate voltage (R	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	500	V
Gate-source voltage		V <sub>GSS</sub>	±30	V
Drain current	DC (Note 1)	I <sub>D</sub>	12	Α
	Pulse (Note 1)	I <sub>DP</sub>	48	Α
Drain power dissipatio	n (Tc = 25°C)	$P_{D}$	40	W
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	324	mJ
Avalanche current		I <sub>AR</sub>	12	Α
Repetitive avalanche	energy (Note 3)	E <sub>AR</sub>	4.0	mJ
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature r	ange	T <sub>stg</sub>	-55~150	°C

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Weight: 1.9 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.125	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

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Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 3.83 mH,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = 12 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

2SK3313



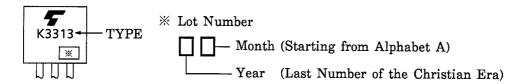
## **Electrical Characteristics (Ta = 25°C)**

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V		_	±10	μΑ
Gate-source bre	eakdown voltage	V (BR) GSS	I <sub>G</sub> = ±100 μA, V <sub>DS</sub> = 0 V	±30	_	_	V
Drain cut-off cu	rent	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V	-	_	100	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	500	_	_	V
Gate threshold v	roltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source O	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A	_	0.5	0.62	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A	3.0	8.5	_	S
Input capacitano	e	C <sub>iss</sub>			2040	_	pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	210	_	
Output capacitance		C <sub>oss</sub>		_	630	_	
Switching time	Rise time	tr	$V_{GS} = 10V$ $V_{GS} = 10V$ $V_{OUT}$ $V_{OUT}$ $V_{DD} = 200V$ $V_{DD} = 10\mu s$	_	22	_	- ns
	Turn-on time	t <sub>on</sub>		_	58	_	
	Fall time	t <sub>f</sub>		_	36	_	
	Turn-off time	t <sub>off</sub>		_	180	_	
Total gate charge (Gate-source plus gate-drain)		Qg			45		
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$		25	_	nC
Gate-drain ("miller") charge		$Q_{gd}$			20	_	

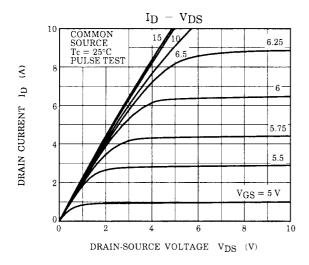
### **Source-Drain Ratings and Characteristics (Ta = 25°C)**

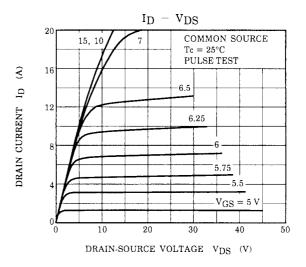
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	-	_	_	12	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	-	_	_	48	Α
Forward voltage (diode)	$V_{DSF}$	I <sub>DR</sub> = 12 A, V <sub>GS</sub> = 0 V	_	_	-1.7	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 12 A, V <sub>GS</sub> = 0 V	_	90	160	ns
Reverse recovery charge	$Q_{rr}$	dI <sub>DR</sub> / dt = 100 A / μs	_	0.25	_	μC

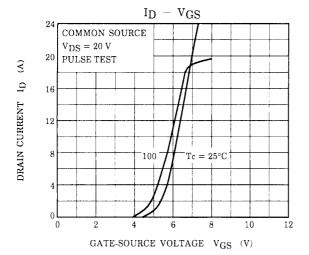
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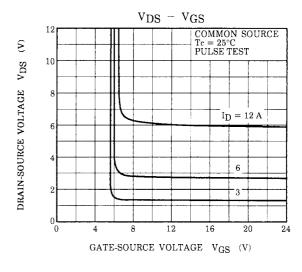


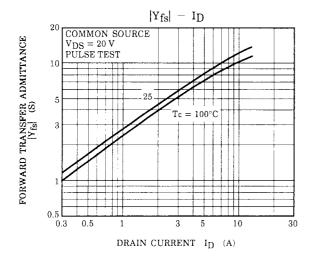
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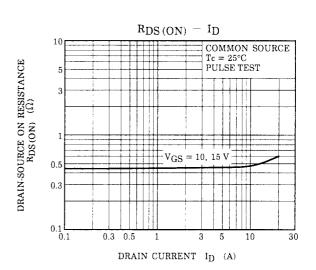




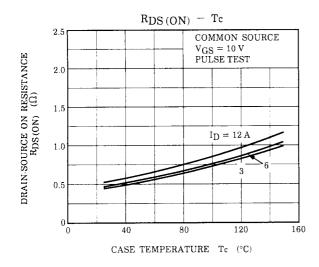


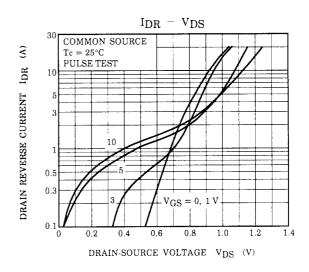


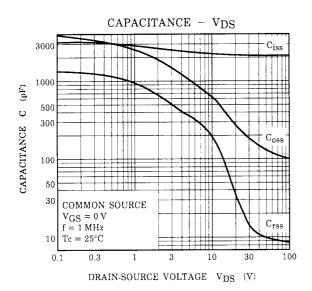


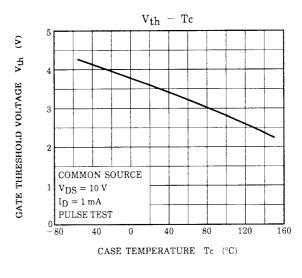


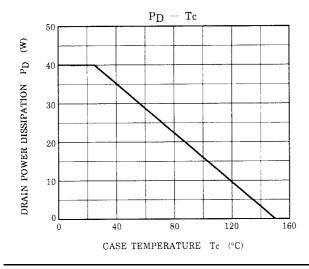
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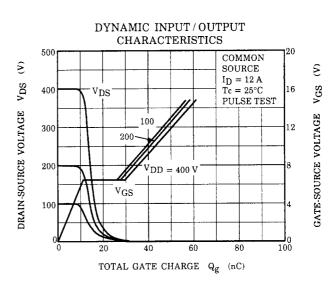




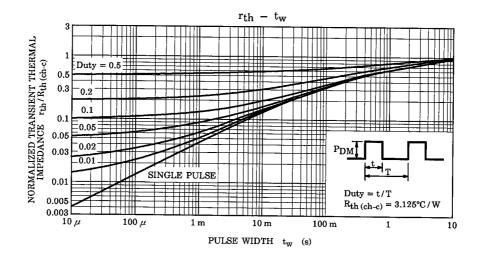


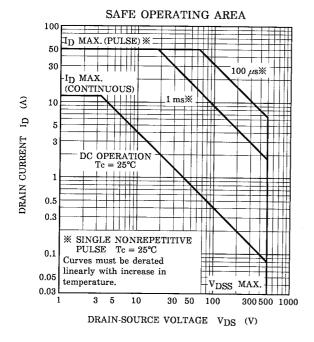


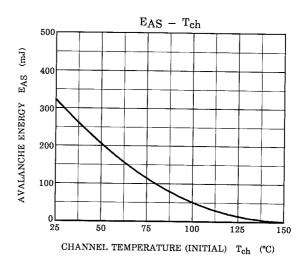


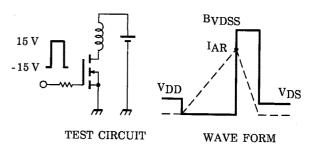


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 3.83~mH \end{aligned} \quad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{BVDSS}{BVDSS - VDD} \right) \end{aligned}$$

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